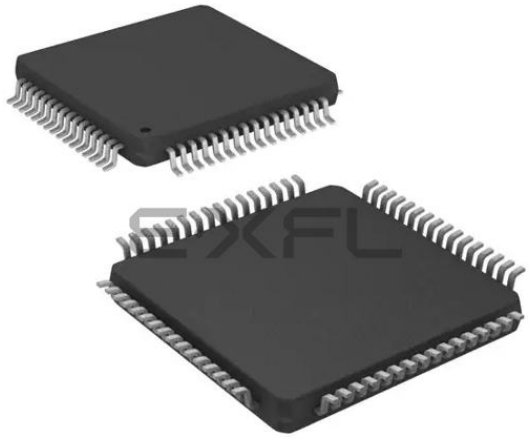
Microchip Technology - DSPIC33EP64GS506T-E/PT Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

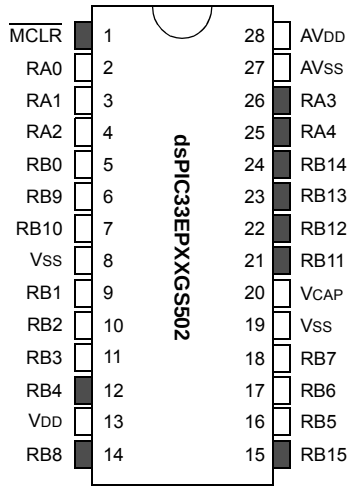
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 22x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64gs506t-e-pt

Pin Diagrams

28-Pin SOIC

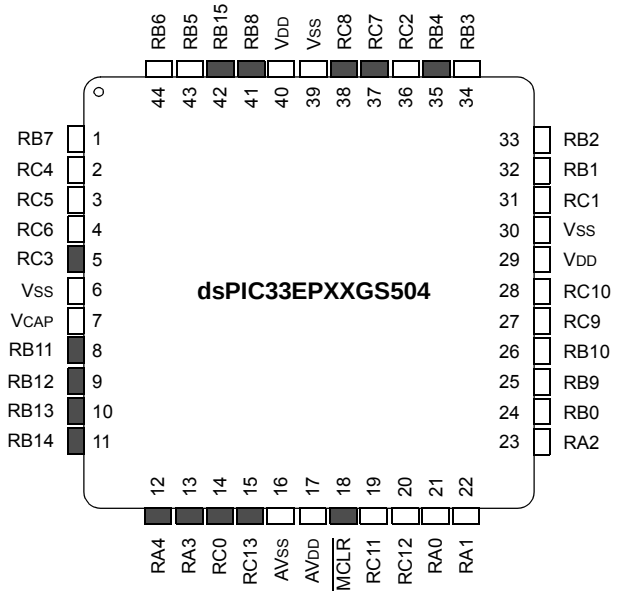


Pin	Pin Function	Pin	Pin Function
1	MCLR	15	PGEC3/SCL2/**RP47**/RB15
2	AN0/PGA1P1/CMP1A/RA0	16	TDO/AN19/PGA2N2/**RP37**/RB5
3	AN1/PGA1P2/PGA2P1/CMP1B/RA1	17	PGED1/TDI/AN20/SCL1/**RP38**/RB6
4	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	18	PGEC1/AN21/SDA1/**RP39**/RB7
5	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	19	VSS
6	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	20	VCAP
7	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	21	TMS/PWM3H/**RP43**/RB11
8	Vss	22	TCK/PWM3L/**RP44**/RB12
9	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	23	PWM2H/**RP45**/RB13
10	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	24	PWM2L/**RP46**/RB14
11	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3	25	PWM1H/RA4
12	PGEC2/ADTRG31/EXTREF1/RP36/RB4	26	PWM1L/RA3
13	VDD	27	AVSS
14	PGED3/SDA2/FLT31/RP40/RB8	28	AVDD

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

44-Pin TQFP



Pin	Pin Function	Pin	Pin Function
1	PGEC1/AN21/SDA1/**RP39**/RB7	23	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2
2	AN1ALT/**RP52**/RC4	24	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0
3	AN0ALT/**RP53**/RC5	25	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9
4	AN17/**RP54**/RC6	26	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10
5	**RP51**/RC3	27	AN11/PGA1N3/**RP57**/RC9
6	VSS	28	AN10/PGA1P4/EXTREF2/**RP58**/RC10
7	VCAP	29	VDD
8	TMS/PWM3H/**RP43**/RB11	30	VSS
9	TCK/PWM3L/**RP44**/RB12	31	AN8/PGA2P4/CMP4C/**RP49**/RC1
10	PWM2H/**RP45**/RB13	32	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1
11	PWM2L/**RP46**/RB14	33	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2
12	PWM1H/RA4	34	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3
13	PWM1L/RA3	35	PGEC2/ADTRG31/**RP36**/RB4
14	FLT12/**RP48**/RC0	36	AN9/CMP4D/EXTREF1/**RP50** /RC2
15	FLT11/**RP61**/RC13	37	ASDA1/**RP55**/RC7
16	AVSS	38	ASCL1/**RP56**/RC8
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	AN12/ISRC1/**RP59**/RC11	41	PGED3/SDA2/FLT31/**RP40**/RB8
20	AN14/PGA2N3/**RP60**/RC12	42	PGEC3/SCL2/**RP47**/RB15
21	AN0/PGA1P1/CMP1A/RA0	43	TDO/AN19/PGA2N2/**RP37**/RB5
22	AN1/PGA1P2/PGA2P1/CMP1B/RA1	44	PGED1/TDI/AN20/SCL1/**RP38**/RB6

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name(1)	Pin Type	Buffer Type	PPS	Description
AN0-AN21	I	Analog	No	Analog input channels.
AN0ALT-AN1ALT	I	Analog	No	Alternate analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
INT4	I	ST	No	External Interrupt 4.
RA0-RA4	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD0-RD15	I/O	ST	No	PORTD is a bidirectional I/O port.
T1CK	I	ST	Yes	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	Yes	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
$\overline{U1CTS}$	I	ST	Yes	UART1 Clear-to-Send.
$\overline{U1RTS}$	O	—	Yes	UART1 Request-to-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	Yes	UART1 IrDA® baud clock output.
$\overline{U2CTS}$	I	ST	Yes	UART2 Clear-to-Send.
$\overline{U2RTS}$	O	—	Yes	UART2 Request-to-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
BCLK2	O	ST	Yes	UART2 IrDA baud clock output.
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	Yes	SPI1 data in.
$\overline{SDO1}$	O	—	Yes	SPI1 data out.
$\overline{SS1}$	I/O	ST	Yes	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
$\overline{SDO2}$	O	—	Yes	SPI2 data out.
$\overline{SS2}$	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXGS50X family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins
  regardless if ADC module is not used (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins
  used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins
  when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
PWM Secondary Special Event Match	81	73	0x0000A6	IFS4<9>	IEC4<9>	IPC18<6:4>
Reserved	82-101	74-93	0x0000A8-0x0000CE	—	—	—
PWM1 – PWM1 Interrupt	102	94	0x0000D0	IFS5<14>	IEC5<14>	IPC23<10:8>
PWM2 – PWM2 Interrupt	103	95	0x0000D2	IFS5<15>	IEC5<15>	IPC23<14:12>
PWM3 – PWM3 Interrupt	104	96	0x0000D4	IFS6<0>	IEC6<0>	IPC24<2:0>
PWM4 – PWM4 Interrupt	105	97	0x0000D6	IFS6<1>	IEC6<1>	IPC24<6:4>
PWM5 – PWM5 Interrupt	106	98	0x0000D8	IFS6<2>	IEC6<2>	IPC24<10:8>
Reserved	106-110	99-102	0x0000DA-0x0000E0	—	—	—
CMP2 – Analog Comparator 2 Interrupt	111	103	0x0000E2	IFS6<7>	IEC6<7>	IPC25<14:12>
CMP3 – Analog Comparator 3 Interrupt	112	104	0x0000E4	IFS6<8>	IEC6<8>	IPC26<2:0>
CMP4 – Analog Comparator 4 Interrupt	113	105	0x0000E6	IFS6<9>	IEC6<9>	IPC26<6:4>
Reserved	114-117	106-109	0x0000E8-0x0000EE	—	—	—
AN0 Conversion Done	118	110	0x0000F0	IFS6<14>	IEC6<14>	IPC27<10:8>
AN1 Conversion Done	119	111	0x0000F2	IFS6<15>	IEC6<15>	IPC27<14:12>
AN2 Conversion Done	120	112	0x0000F4	IFS7<0>	IEC7<0>	IPC28<2:0>
AN3 Conversion Done	121	113	0x0000F6	IFS7<1>	IEC7<1>	IPC28<6:4>
AN4 Conversion Done	122	114	0x0000F8	IFS7<2>	IEC7<2>	IPC28<10:8>
AN5 Conversion Done	123	115	0x0000FA	IFS7<3>	IEC7<3>	IPC28<14:12>
AN6 Conversion Done	124	116	0x0000FC	IFS7<4>	IEC7<4>	IPC29<2:0>
AN7 Conversion Done	125	117	0x0000FE	IFS7<5>	IEC7<5>	IPC29<6:4>
Reserved	126-149	118-141	0x000100-0x00012E	—	—	—
ICD – ICD Application	150	142	0x000130	IFS8<14>	IEC8<14>	IPC35<10:8>
JTAG – JTAG Programming	151	143	0x000132	IFS8<15>	IEC8<15>	IPC35<14:12>
Reserved	152-158	144-150	0x000134-0x000140	—	—	—
AN8 Conversion Done	159	151	0x000142	IFS9<7>	IEC9<7>	IPC37<14:12>
AN9 Conversion Done	160	152	0x000144	IFS9<8>	IEC9<8>	IPC38<2:0>
AN10 Conversion Done	161	153	0x000146	IFS9<9>	IEC9<9>	IPC38<6:4>
AN11 Conversion Done	162	154	0x000148	IFS9<10>	IEC9<10>	IPC38<10:8>
AN12 Conversion Done	163	155	0x00014A	IFS9<11>	IEC9<11>	IPC38<14:12>
AN13 Conversion Done	164	156	0x00014C	IFS9<12>	IEC9<12>	IPC39<2:0>
AN14 Conversion Done	165	157	0x00014E	IFS9<13>	IEC9<13>	IPC39<6:4>
AN15 Conversion Done	166	158	0x000150	IFS9<14>	IEC9<14>	IPC39<10:8>
AN16 Conversion Done	167	159	0x000152	IFS9<15>	IEC9<15>	IPC39<14:12>
AN17 Conversion Done	168	160	0x000154	IFS10<0>	IEC10<0>	IPC40<2:0>
AN18 Conversion Done	169	161	0x000156	IFS10<1>	IEC10<1>	IPC40<6:4>
AN19 Conversion Done	170	162	0x000158	IFS10<2>	IEC10<2>	IPC40<10:8>
AN20 Conversion Done	171	163	0x00015A	IFS10<3>	IEC10<3>	IPC40<14:12>
AN21 Conversion Done	172	164	0x00015C	IFS10<4>	IEC10<4>	IPC41<2:0>
Reserved	173-180	165-172	0x00015C-0x00016C	—	—	—
I2C1 – I2C1 Bus Collision	181	173	0x00016E	IFS10<13>	IEC10<13>	IPC43<6:4>
I2C2 – I2C2 Bus Collision	182	174	0x000170	IFS10<14>	IEC10<14>	IPC43<10:8>
Reserved	183-184	175-176	0x000172-0x000174	—	—	—
ADCMP0 – ADC Digital Comparator 0	185	177	0x000176	IFS11<1>	IEC11<1>	IPC44<6:4>
ADCMP1 – ADC Digital Comparator 1	186	178	0x000178	IFS11<2>	IEC11<2>	IPC44<10:8>
ADFLTR0 – ADC Filter 0	187	179	0x00017A	IFS11<3>	IEC11<3>	IPC44<14:12>
ADFLTR1 – ADC Filter 1	188	180	0x00017C	IFS11<4>	IEC11<4>	IPC45<2:0>
Reserved	189-253	181-245	0x00017E-0x0001FE	—	—	—

8.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator Module"** (DS70005131) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

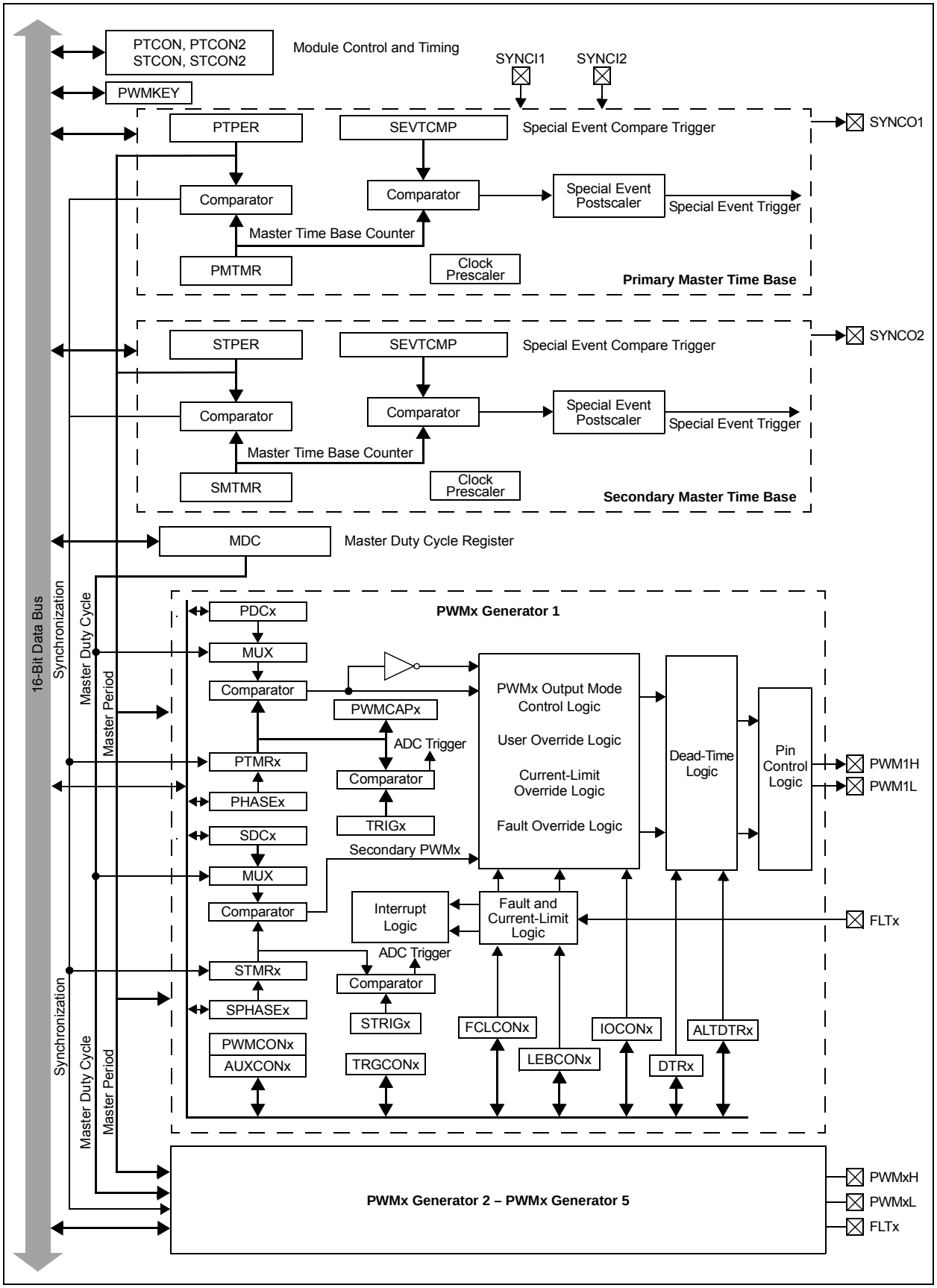
The dsPIC33EPXXGS50X family oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection
- Auxiliary PLL for ADC and PWM

A simplified diagram of the oscillator system is shown in Figure 8-1.

NOTES:

FIGURE 15-2: SIMPLIFIED CONCEPTUAL BLOCK DIAGRAM OF THE HIGH-SPEED PWM



REGISTER 15-10: MDC: PWMx MASTER DUTY CYCLE REGISTER(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
MDC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
MDC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **MDC<15:0>:** PWMx Master Duty Cycle Value bits

Note 1: The smallest pulse width that can be generated on the PWMx output corresponds to a value of 0x0008, while the maximum pulse width generated corresponds to a value of Period – 0x0008.

2: As the duty cycle gets closer to 0% or 100% of the PWMx period (0 to 40 ns, depending on the mode of operation), PWMx duty cycle resolution will increase from 1 to 3 LSBs.

REGISTER 15-11: PWMKEY: PWMx PROTECTION LOCK/UNLOCK KEY REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PWMKEY<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PWMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PWMKEY<15:0>:** PWMx Protection Lock/Unlock Key Value bits

REGISTER 15-17: DTRx: PWMx DEAD-TIME REGISTER (x = 1 to 5)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTRx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-0 **DTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

REGISTER 15-18: ALTDTRx: PWMx ALTERNATE DEAD-TIME REGISTER (x = 1 to 5)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	ALTDTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALTDTRx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-0 **ALTDTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

NOTES:

REGISTER 18-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 5 **ABAUD:** Auto-Baud Enable bit
1 = Enables baud rate measurement on the next character – requires reception of a Sync field (55h) before other data; cleared in hardware upon completion
0 = Baud rate measurement is disabled or completed

bit 4 **URXINV:** UARTx Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = BRG generates 4 clocks per bit period (4x baud clock, High-Speed mode)
0 = BRG generates 16 clocks per bit period (16x baud clock, Standard mode)

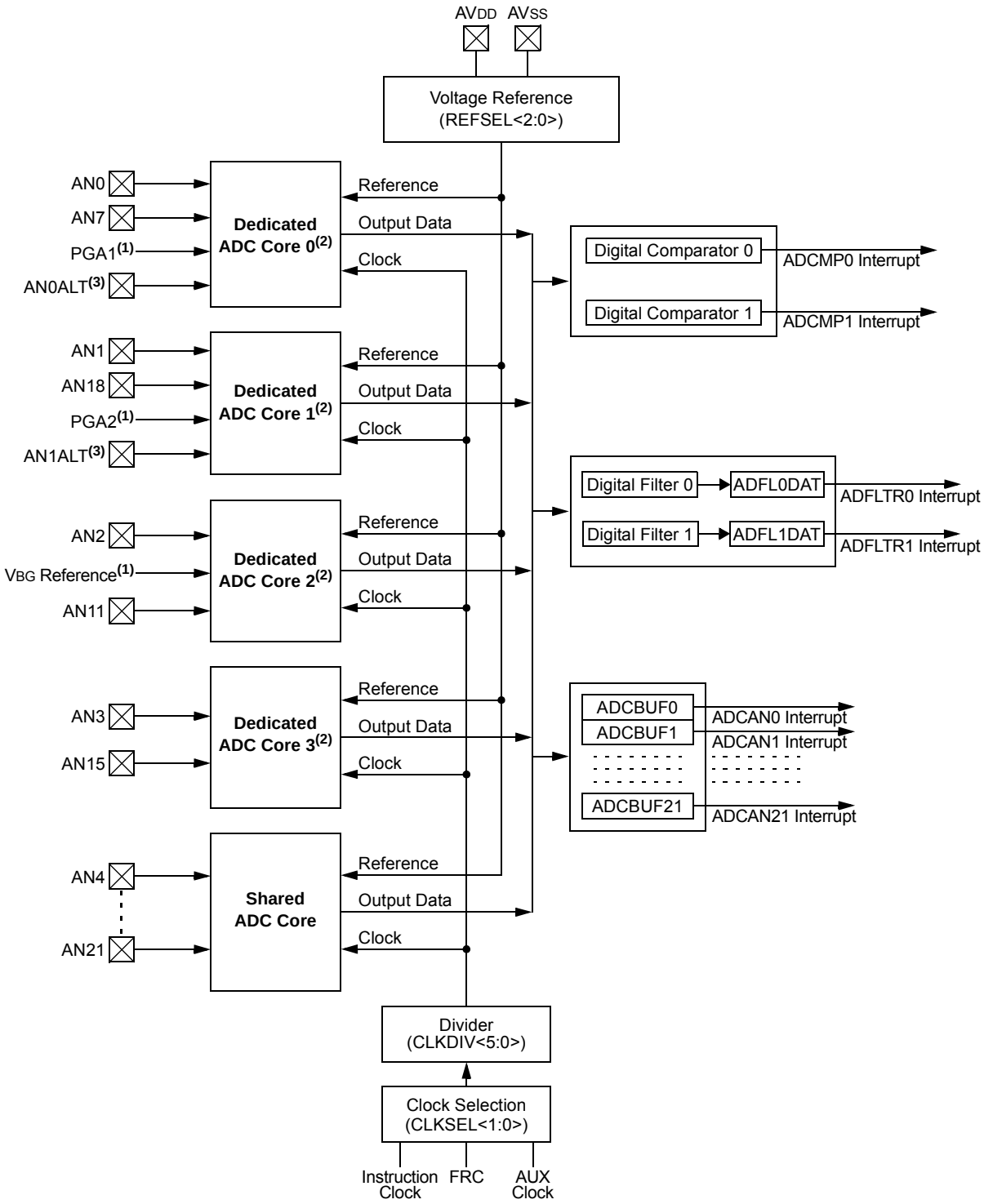
bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Bit Selection bit
1 = Two Stop bits
0 = One Stop bit

Note 1: Refer to **"Universal Asynchronous Receiver Transmitter (UART)"** (DS70000582) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UARTx module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

FIGURE 19-1: ADC MODULE BLOCK DIAGRAM



Note 1: PGA1, PGA2 and Band Gap Reference (V_{BG}) are internal analog inputs and are not available on device pins.
2: If the dedicated core uses an alternate channel, then shared core function cannot be used.
3: AN0ALT and AN1ALT are not available on dsPIC33EPXXGS502 devices.

23.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33EPXXGS50X family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation
- Brown-out Reset (BOR)

23.1 Configuration Bits

In dsPIC33EPXXGS50X family devices, the Configuration Words are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored at the end of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 23-1 with detailed descriptions in Table 23-2. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration Shadow registers during device Resets.

For devices operating in Dual Partition modes, the BSEQx bits (FBTSEQ<11:0>) determine which panel is the Active Partition at start-up and the Configuration Words from that panel are loaded into the Configuration Shadow registers.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Words for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled. Program code executing out of configuration space will cause a device Reset.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration Words.

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(1)	Status Flags Affected
26	CTXTSWP	CTXTSWP #1it3	Switch CPU register context to context defined by lit3	1	2	None
		CTXTSWP Wn	Switch CPU register context to context defined by Wn	1	2	None
27	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
28	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
29	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
30	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None
31	DIV	DIV.S Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
32	DIVF	DIVF Wm,Wn	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
33	DO	DO #lit15,Expr	Do code to PC + Expr, lit15 + 1 time	2	2	None
		DO Wn,Expr	Do code to PC + Expr, (Wn) + 1 time	2	2	None
34	ED	ED Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
35	EDAC	EDAC Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
36	EXCH	EXCH Wns,Wnd	Swap Wns with Wnd	1	1	None
37	FBCL	FBCL Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
38	FF1L	FF1L Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
39	FF1R	FF1R Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
40	GOTO	GOTO Expr	Go to address	2	4	None
		GOTO Wn	Go to indirect	1	4	None
		GOTO.L Wn	Go to indirect (long address)	1	4	None
41	INC	INC f	f = f + 1	1	1	C,DC,N,OV,Z
		INC f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
42	INC2	INC2 f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2 f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2 Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
43	IOR	IOR f	f = f .IOR. WREG	1	1	N,Z
		IOR f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR #lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
44	LAC	LAC Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
45	LNK	LNK #lit14	Link Frame Pointer	1	1	SFA
46	LSR	LSR f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
47	MAC	MAC Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

25.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

25.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

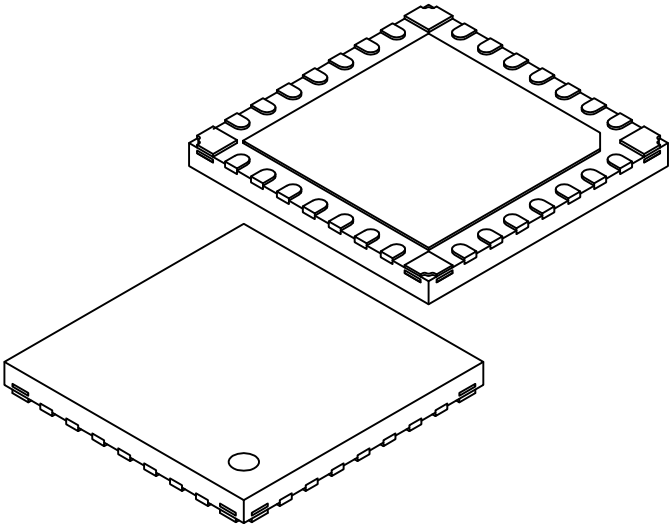
- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (2N) - 6x6x0.55 mm Body [UQFN] With 4.65x4.65 mm Exposed Pad and Corner Anchors

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.55	4.65	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.55	4.65	4.75
Exposed Pad Corner Chamfer	P	-	0.35	-
Terminal Width	b	0.25	0.30	0.35
Corner Anchor Pad	b1	0.35	0.40	0.43
Corner Pad, Metal Free Zone	b2	0.15	0.20	0.25
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

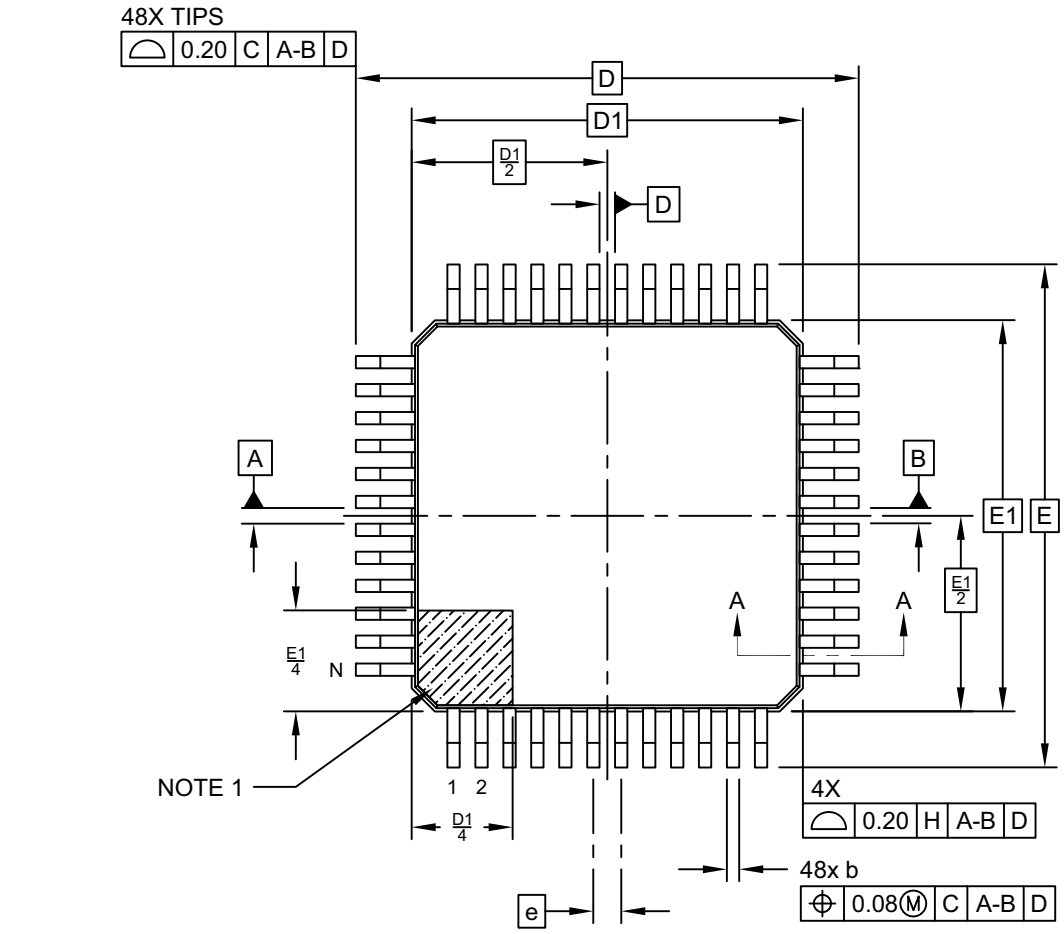
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

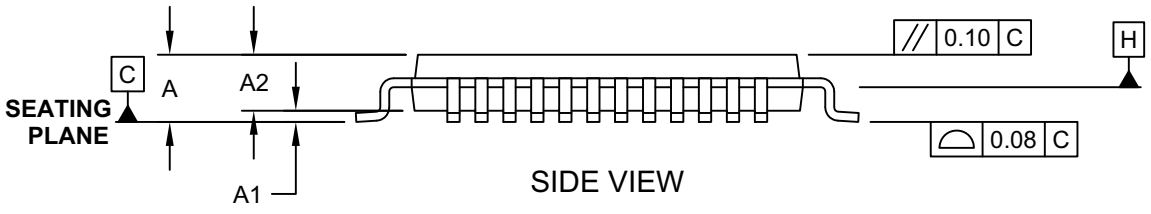
Microchip Technology Drawing C04-385B Sheet 2 of 2

48-Lead Thin Quad Flatpack (Y8) - 7x7x1.0 mm Body [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW

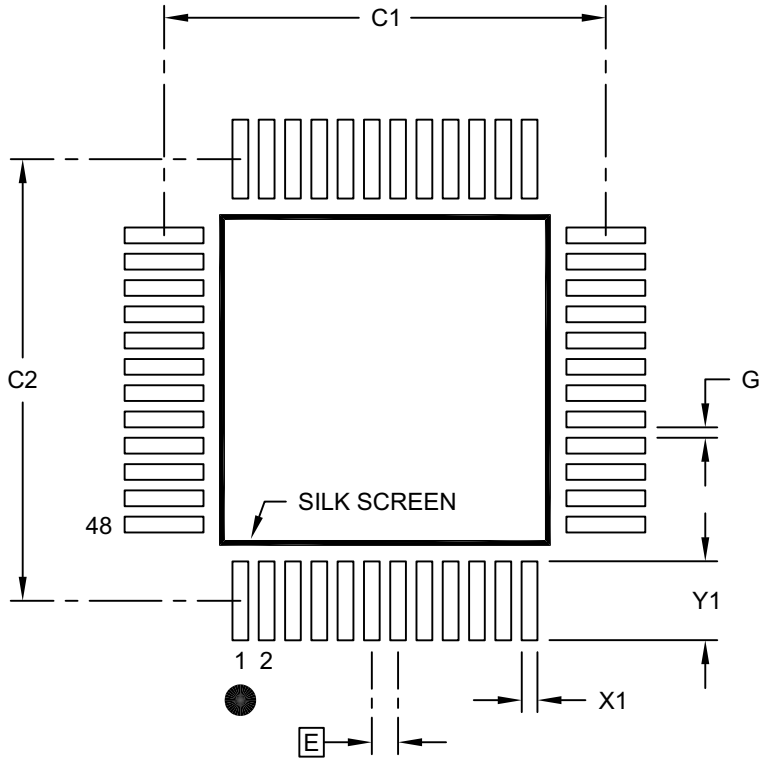


SIDE VIEW

Microchip Technology Drawing C04-300-Y8 Rev A Sheet 1 of 2

48-Lead Thin Quad Flatpack (Y8) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		8.40	
Contact Pad Spacing	C2		8.40	
Contact Pad Width (X48)	X1			0.30
Contact Pad Length (X48)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2300-Y8 Rev A

INDEX